International IOR Rectifier

POWER MOSFET THRU-HOLE (TO-257AA)

IRFY044,IRFY044M **60V, N-CHANNEL HEXFET® MOSFET TECHNOLOGY**

Product Summary

Part Number	RDS(on)	ΙD	Eyelets
IRFY044	0.040 Ω	16*A	Glass
IRFY044M	0.040 Ω	16*A	Glass

HEXFET® MOSFET technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry design achieves very low on-state resistance combined with high transconductance. HEXFET transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching, ease of paralleling and electrical parameter temperature stability. They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers, high energy pulse circuits, and virtually any application where high reliability is required. The HEXFET transistor's totally isolated package eliminates the need for additional isolating material between the device and the heatsink. This improves thermal efficiency and reduces drain capacitance.



Features:

- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed
- Electrically Isolated
- Glass Eyelets
- For Space Level Applications Refer to Ceramic Version Part Numbers IRFY044C, IRFY044CM

Absolute Maximum Ratings

	Parameter		Units
ID @ VGS = 10V, TC = 25°C	Continuous Drain Current	16*	
ID @ VGS = 10V, TC = 100°C	Continuous Drain Current	16*	Α
IDM	Pulsed Drain Current ①	156	
P _D @ T _C = 25°C	Max. Power Dissipation	100	W
	Linear Derating Factor	0.8	W/°C
VGS	Gate-to-Source Voltage	±20	V
EAS	Single Pulse Avalanche Energy ②	100	mJ
IAR	Avalanche Current ①	16*	Α
EAR	Repetitive Avalanche Energy ①	10	mJ
dv/dt	Peak Diode Recovery dv/dt 3	4.5	V/ns
TJ	Operating Junction	-55 to 150	
TSTG	Storage Temperature Range		°C
	Lead Temperature	300(0.063in./1.6mm from case for 10 sec)	
	Weight	3.3 (Typical)	g

^{*} Current is limited by pin diameter For footnotes refer to the last page

Electrical Characteristics @ Tj = 25°C (Unless Otherwise Specified)

	Parameter	Min	Тур	Max	Units	Test Conditions
BVDSS	Drain-to-Source Breakdown Voltage	60		_	V	VGS = 0V, ID = 1.0mA
ΔBV _{DSS} /ΔT _J	Temperature Coefficient of Breakdown Voltage	_	0.68	_	V/°C	Reference to 25°C, I _D = 1.0mA
RDS(on)	Static Drain-to-Source On-State Resistance	_	_	0.04	Ω	VGS = 10V, ID = 16A (4)
VGS(th)	Gate Threshold Voltage	2.0	_	4.0	V	V _{DS} = V _{GS} , I _D = 250μA
9fs	Forward Transconductance	17	_	_	S (7)	V _{DS} > 15V, I _{DS} = 16A ④
IDSS	Zero Gate Voltage Drain Current	_	_	25		V _{DS} = 48V ,V _{GS} =0V
		_	_	250	μΑ	V _{DS} = 48V,
						VGS = 0V, TJ = 125°C
IGSS	Gate-to-Source Leakage Forward	_	_	100	- 4	VGS = 20V
IGSS	Gate-to-Source Leakage Reverse	_	_	-100	nA	VGS = -20V
Qg	Total Gate Charge		_	88		VGS =10V, ID = 16A
Qgs	Gate-to-Source Charge	_	_	15	nC	V _{DS} = 30V
Q _{gd}	Gate-to-Drain ('Miller') Charge	_	_	52	1	
td(on)	Turn-On Delay Time		_	23		$V_{DD} = 30V, I_{D} = 16A,$
tr	Rise Time		_	130		$R_G = 9.1\Omega$
td(off)	Turn-Off Delay Time		_	81	ns	
tf	Fall Time	_	_	79		
LS+LD	Total Inductance	_	6.8	_	nΗ	Measured from drain lead (6mm/0.25in. from package) to source lead (6mm/0.25in. from package)
C _{iss}	Input Capacitance	_	2400	_		VGS = 0V, VDS = 25V
Coss	Output Capacitance		1100	_	pF	f = 1.0MHz
C _{rss}	Reverse Transfer Capacitance	_	230	_		

Source-Drain Diode Ratings and Characteristics

	Parameter	Min	Тур	Max	Units	Test Conditions
IS	Continuous Source Current (Body Diode)	_	_	16*	Α	
ISM	Pulse Source Current (Body Diode) ①		_	156	, ,	
VSD	Diode Forward Voltage		_	2.5	V	$T_j = 25$ °C, $I_S = 16A$, $V_{GS} = 0V$ ④
t _{rr}	Reverse Recovery Time		_	220	nS	Tj = 25°C, IF = 16A, di/dt ≤ 100A/μs
QRR	R Reverse Recovery Charge		_	1.6	μC	V _{DD} ≤ 50V ④
ton	Forward Turn-On Time Intrinsic turn-on	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $L_S + L_D$.				

^{*} Current is limited by pin diameter

Thermal Resistance

	Parameter	Min	Тур	Max	Units	Test Conditions
RthJC	Junction-to-Case	_	_	1.25		
RthCS	Case-to-sink	_	0.21	_	°C/W	
R _{th} JA	Junction-to-Ambient	_	_	80		Typical socket mount

Note: Corresponding Spice and Saber models are available on the G&S Website.

For footnotes refer to the last page

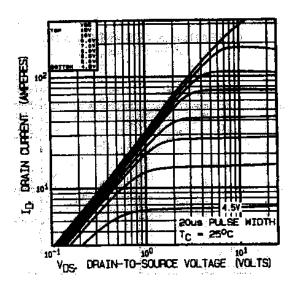


Fig 1. Typical Output Characteristics

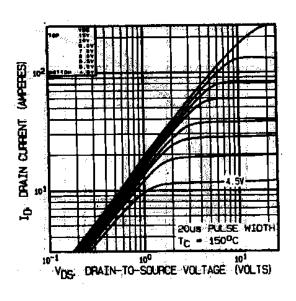


Fig 2. Typical Output Characteristics

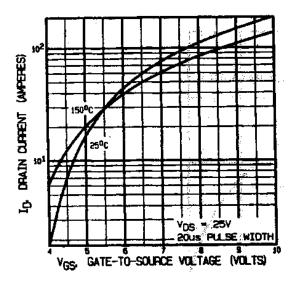


Fig 3. Typical Transfer Characteristics

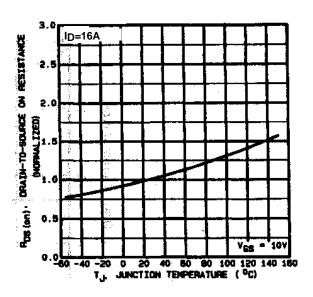


Fig 4. Normalized On-Resistance Vs. Temperature

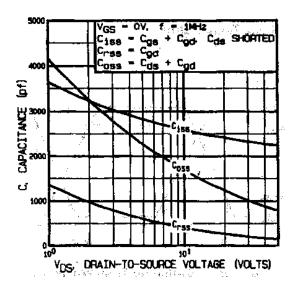


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

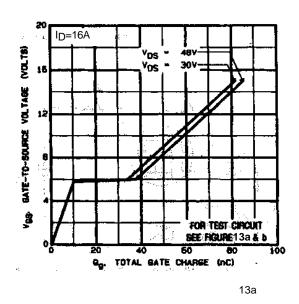


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

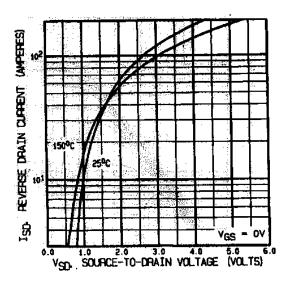


Fig 7. Typical Source-Drain Diode Forward Voltage

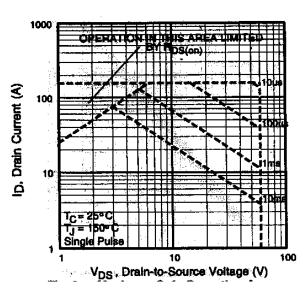


Fig 8. Maximum Safe Operating Area

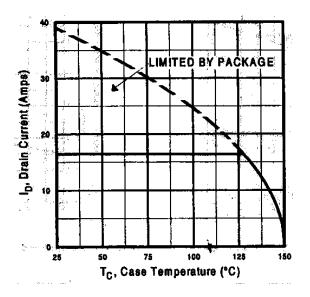


Fig 9. Maximum Drain Current Vs. Case Temperature

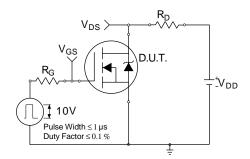


Fig 10a. Switching Time Test Circuit

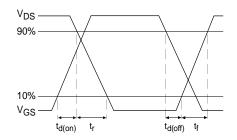


Fig 10b. Switching Time Waveforms

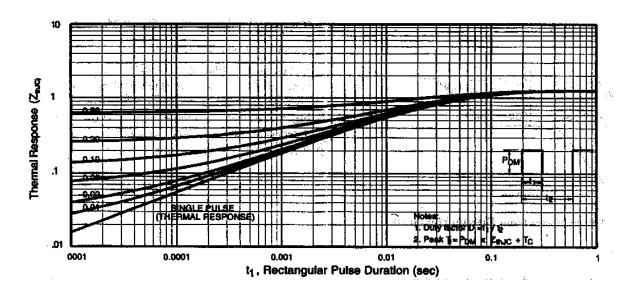


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

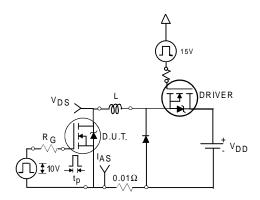
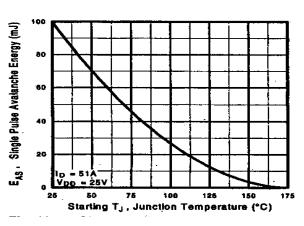


Fig 12a. Unclamped Inductive Test Circuit



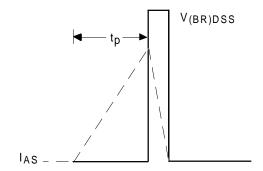


Fig 12b. Unclamped Inductive Waveforms

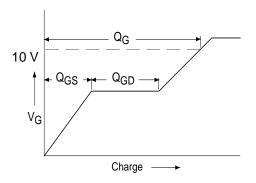


Fig 13a. Basic Gate Charge Waveform

Fig 12c. Maximum Avalanche Energy Vs. Drain Current

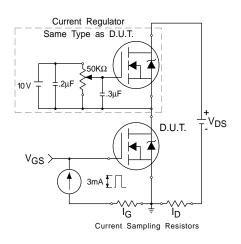
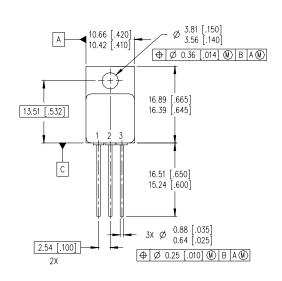


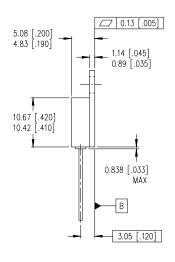
Fig 13b. Gate Charge Test Circuit

Foot Notes:

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- ② VDD = 25V, starting TJ = 25°C, L= 0.78mH Peak IL = 16A, VGS = 10V
- $\label{eq:local_state} \begin{tabular}{ll} \begin{tabular}{ll}$
- 4 Pulse width \leq 300 μs ; Duty Cycle \leq 2%

Case Outline and Dimensions — TO-257AA





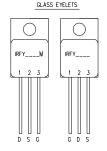
NOTES:

- DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1994.
- 2. CONTROLLING DIMENSION: INCH.
- 3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
- 4. OUTLINE CONFORMS TO JEDEC OUTLINE TO-257AA.

<u>LEGEND</u> D – DRAIN

S - SOURCE

G - GATE





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